Gap Pad® 2500

Thermally Conductive, Un-Reinforced Gap Filling Material

Features and Benefits

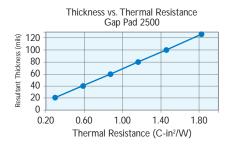
- Thermal conductivity: 2.7 W/m-K
- High thermal performance, cost-effective solution
- · Un-reinforced construction for additional compliancy
- · Medium compliancy and conformability



Gap Pad 2500 is a thermally conductive, electrically insulating, un-reinforced gap filling material. Gap Pad 2500 is a filled-polymer material yielding an elastic polymer that allows for easy handling and converting without the need for reinforcement. These properties also allow for good wet-out and interfacing characteristics to surfaces with roughness and/or topography. All these characteristics make this material ideal for applications using either clip or screw-mounted assemblies.

Gap Pad 2500 is offered with inherent natural tack on both sides of the material allowing for stick-in-place characteristics during application assembly. The material is supplied with protective liners on both sides.

Note: Resultant thickness is defined as the final gap thickness of the application.



TYPICAL PROPERTIES OF GAP PAD 2500			
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD
Color	Light Brown	Light Brown	Visual
Reinforcement Carrier	_	_	_
Thickness (inch) / (mm)	0.020 to 0.125	0.508 to 3.175	ASTM D374
Inherent Surface Tack (1- or 2-sided)	2	2	_
Density (g/cc)	3.1	3.1	ASTM D792
Heat Capacity (J/g-K)	1.0	1.0	ASTM E1269
Hardness, Bulk Rubber (Shore 00) (1)	80	80	ASTM D2240
Young's Modulus (psi) / (kPa) (2)	113	779	ASTM D575
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200	_
ELECTRICAL			
Dielectric Breakdown Voltage (Vac)	>6000	>6000	ASTM D149
Dielectric Constant (1000 Hz)	6.8	6.8	ASTM D150
Volume Resistivity (Ohm-meter)	1011	1011	ASTM D257
Flame Rating	V-O	V-O	U.L. 94
THERMAL			
Thermal Conductivity (W/m-K)	2.7	2.7	ASTM D5470
1) Thirty account dolouvalue Charo 00 hardness cools			

- 1) Thirty second delay value Shore 00 hardness scale.
 2) Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch². For more information on Gap Pad modulus, refer to Bergquist Application Note #116.

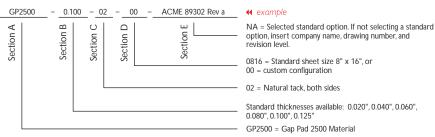
Typical Applications Include:

- Multiple heat-generating components to a common heat sink
- · Graphics chips to heat sinks
- · Processors to heat sinks
- Mass storage drives
- Wireline / wireless communications hardware

Configurations Available:

• Sheet form and die-cut parts

Building a Part Number



Note: To build a part number, visit our website at www.bergquistcompany.com

Gap Pad®: U.S. Patent 5,679,457 and others



www.bergquistcompany.com

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The Bergquist Company - Asia No. 38-40, Au Pui Wan Street Fotan, Shatin, N.T. Hong Kong Ph: 852 2690.294 Fax: 852.2690.2344 All statements, technical information and recommendations herein are based on tests we believe to be reliable, and THE FOLLOWING IS MADE IN LIEU OF ALL WARRANTIES, EXPRESSED OR IMPLIED, INCLUDING THE IMPLIED WARRANTIES OF MARKETABILITY AND FITNESS FOR PURPOSE. Sellers' and manufacturers' only obligation shall be to replace such quantity of the product proved to be defective. Before using user shall determine the suitability of the product for its intended use, and the user assumes all risks and liability whatsoever in connection therewith. NEITHER SELLER NOR MANUFACTURER SHALL BE LIABLE EITHER IN TORT OR IN CONTRACT FOR ANY LOSS OR DAMAGE, DIRECT, INCIDENTAL, OR CONSCOUNTIAL, INCLUDING LOSS OF PROFITS OR REVENUE ARSING OUT OF THE USE OR THE INABILITY TO USE A PRODUCT. No statement, purchase order or recommendations by seller or purchaser not contained herein shall have any force or effect unless in an agreement signed by the officers of the seller and manufacturer. PDS GP 2500 12.08

Standard Options